# MAZE062D

## Silicon planar type

For surge absorption circuit

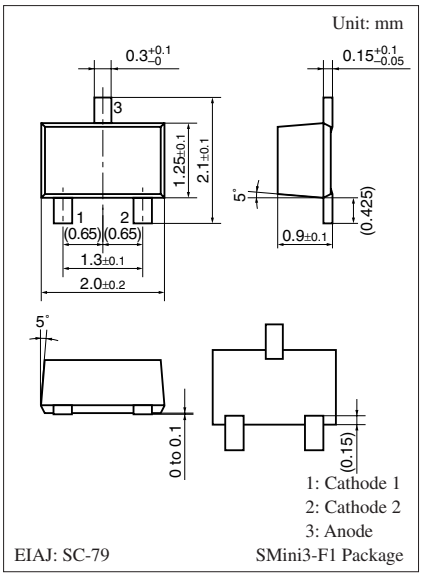
### ■ Features

- Low joint capacity zener diode

### ■ Absolute Maximum Ratings $T_a = 25°C$

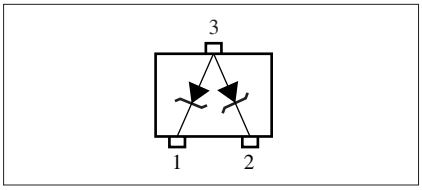
| Parameter | Symbol | Rating | Unit |
|---|---|---|---|
| Repetitive peak forward current | $I_{FRM}$ | 200 | mA |
| Power dissipation * | $P_D$ | 150 | mW |
| Junction temperature | $T_j$ | 150 | °C |
| Storage temperature | $T_{stg}$ | −55 to +150 | °C |

Note) *: $P_D$ = 200 mW achieved with a printed circuit board.




Marking Symbol: 6.2C

Internal connection

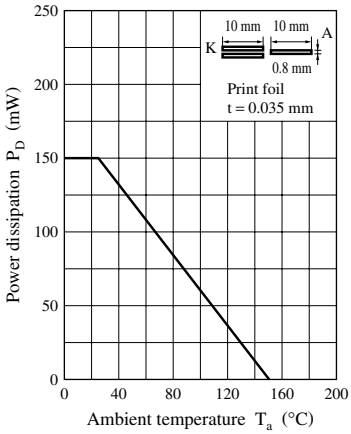



### ■ Electrical Characteristics $T_a = 25°C \pm 3°C$

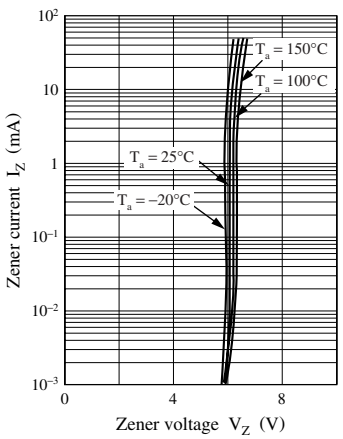
| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| Forward voltage | $V_F$ | $I_F$ = 10 mA | | 0.9 | 1.0 | V |
| Zener voltage * | $V_Z$ | $I_Z$ = 5 mA | 5.9 | | 6.5 | V |
| Zener rise operating resistance | $R_{ZK}$ | $I_Z$ = 0.5 mA | | | 100 | Ω |
| Zener operating resistance | $R_Z$ | $I_Z$ = 5 mA | | | 30 | Ω |
| Reverse current | $I_R$ | $V_R$ = 5.5 V | | | 3 | μA |
| Terminal capacitance | $C_t$ | $V_R$ = 0 V, f = 1 MHz | | 8 | | pF |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 5 MHz.
3. Electrostatic breakdown voltage: ±15 kV
Test method: IEC-801 (C = 150 pF, R = 330 Ω, Contact discharge: 10 times)
Test unit: ESS-200AX
4. *: The $V_Z$ value is for the temperature of 25°C. In other cases, carry out the temperature compensation.
Guaranteed at 20 ms after power application.

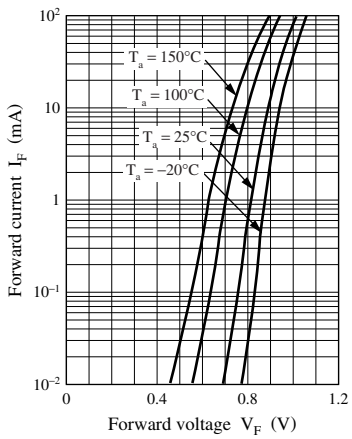
$P_D$ — $T_a$



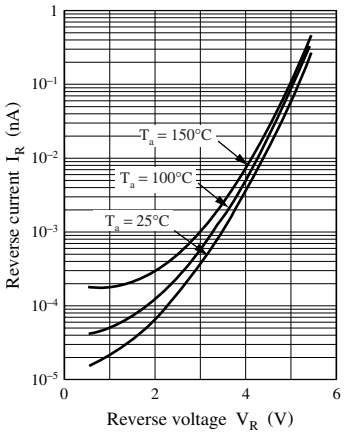

$I_Z$ — $V_Z$



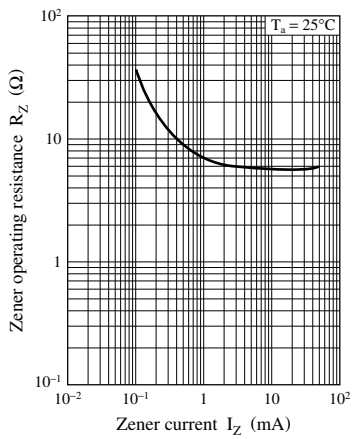

$I_F$ — $V_F$



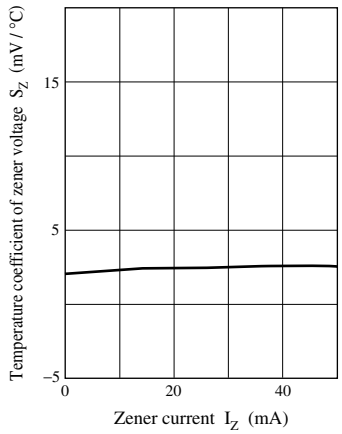

$I_R$ — $V_R$



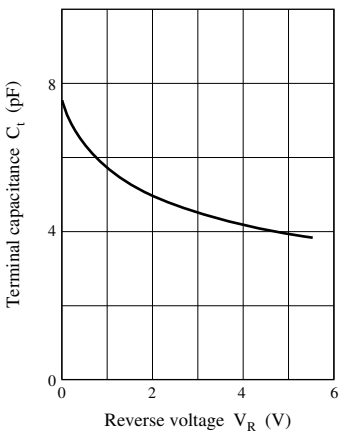

$R_Z$ — $I_Z$




$S_Z$ — $I_Z$




$C_t$ — $V_R$



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